Abstract Of The Disclosure

In the preferred embodiment, there is disclosed a printed circuit board having a surface providing a mating interface to which is electrically connected an electrical connector having signal conductors and ground conductors. The printed circuit board includes a plurality of stacked dielectric layers, with a conductor disposed on at least one of the plurality of dielectric layers. The mating interface includes a plurality of conductive vias aligned in a plurality of rows, with the plurality of conductive vias extending through at least a portion of the plurality of dielectric layers, at least one of the plurality of conductive vias intersecting the conductor. The plurality of conductive vias includes signal conductor connecting conductive vias and ground conductor connecting conductive vias. For each of the plurality of rows of the conductive vias, there are at least twice as many ground conductor connecting conductive vias as signal conductor connecting conductive vias and the conductive vias are positioned relative to one another so that for each signal conductor connecting conductive via, there are ground conductor connecting conductive vias adjacent either side of the signal conductor connecting conductive via.